



FORM PTO-1449

INFORMATION DISCLOSURE CITATION

Attorney Docket:	Serial No.:
4024-4021	09/897,158

Applicant:
Dudoff et al.

Filing Date:	Group Art Unit:
June 29, 2001	2814

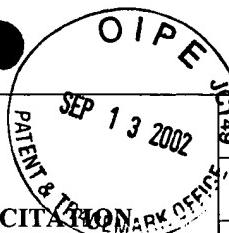
U.S. PATENT DOCUMENTS

Examiner Initial	Patent Number	Publication Date	Name	Class	Sub-Class	Filing Date
Dale	4,533,833		Copeland et al.			August 6, 1985
	5,266,794		Olbright et al.			November 30, 1993
	5,269,453		Melton et al.			December 14, 1993
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	5,477,933		Nguyen			December 26, 1995
	5,793,789		Ben-Michael et al.			April 11, 1998
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	6,172,417		Goossen			September 1995
	6,184,066		Chino et al.			February 6, 2001
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	6,343,171		Yoshimura et al.			June 29, 2002
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	Pub. No. US2001 0038103		Nitta et al			November 8, 2001
	Pub. No. US2001 0081773		Inoue et al.			June 27, 2002

Examiner	<i>Dale Witz</i>	Date Considered
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP §609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.		

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FOREIGN PATENT DOCUMENTS

Examiner Initial	Patent Number	Publication Date	Country	Class	Sub-Class	Translation
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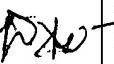
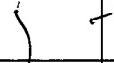
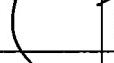
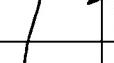
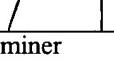
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	Pommerrenig, D.H. et al., "Hybrid silicon focal plane development: an update", SPIE, Vol. 267, pages 23-30, 1981.
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	Sasaki, J. et al., "Self-aligned Assembly Technology for Optical Devices Using AuSn Solder Bumps Flip-Chip Bonding", pages 260-261.
Examiner <i>Douglas Wiles</i>	Date Considered <i>6 nov 02</i>
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